

## N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

## **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

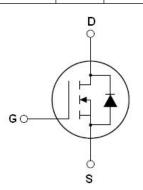
#### **Features**

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

#### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

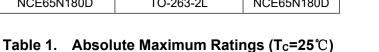
V <sub>DS min@Tjmax</sub>	710	V
R <sub>DS(ON)TYP</sub>	160	mΩ
ID	20	Α
Qg	28.5	nC



Schematic diagram

#### **Package Marking And Ordering Information**

	<u> </u>	
Device	Device Package	Marking
NCE65N180D	TO-263-2L	NCE65N180D





TO-263-2L

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	VDS	650	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	20	А
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	14	А
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	80	А
Maximum Power Dissipation(Tc=25°C)	P <sub>D</sub>	194	W
Derate above 25°C		1.29	W/°C
Avalanche current <sup>(Note 1)</sup>	I <sub>AS</sub>	6	A
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \le 480 \text{ V,I}_{SD} < I_D$	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55+175	°C

<sup>\*</sup> limited by maximum junction temperature



#### **Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	0.77	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

 Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states	'			•	•	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			100	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	3	3.5	4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A		160	180	mΩ
Dynamic Characteristics						
Input Capacitance	C <sub>lss</sub>	V 50VV 0V		1550	1950	pF
Output Capacitance	Coss	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V,		60		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz		5		pF
Total Gate Charge	Qg			28.5		nC
Gate-Source Charge	Qgs	V <sub>DS</sub> =480V,I <sub>D</sub> =10.5A,		11.7		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V		5		nC
Gate plateau voltage	Vgp			5.7		V
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		2		Ω
Switching times	•					
Turn-on Delay Time	t <sub>d(on)</sub>			32		nS
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =380V,I <sub>D</sub> =10A,		18		nS
Turn-Off Delay Time	$t_{d(off)}$	$R_G=1.7\Omega, V_{GS}=10V$		90		nS
Turn-Off Fall Time	t <sub>f</sub>			8		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T 0500			20	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			80	Α
Forward On Voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =20A,V <sub>GS</sub> =0V		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T: 05°0 L 404		300		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I <sub>F</sub> =10A,		4.5		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>	di/dt=100A/μs		30		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25  $^{\circ}\text{C}$  ,VDD=50V,VG=10V, RG=25 $\Omega$ 



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

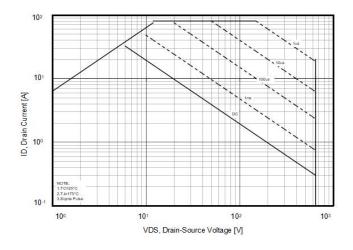


Figure 3. Transfer characteristics

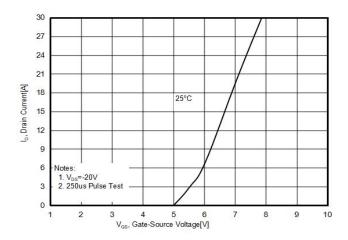


Figure 5. RDS(ON) vs Junction Temperature

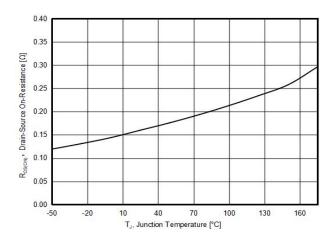


Figure 2. Capacitance

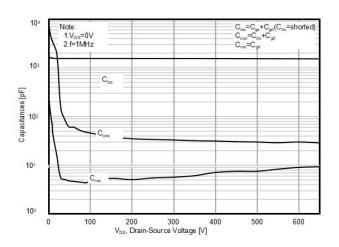


Figure 4. Output characteristics

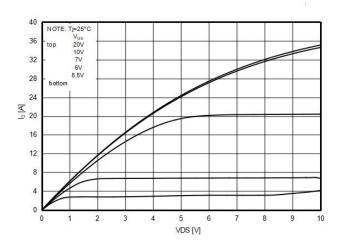


Figure 6. BV<sub>DSS</sub> vs Junction Temperature

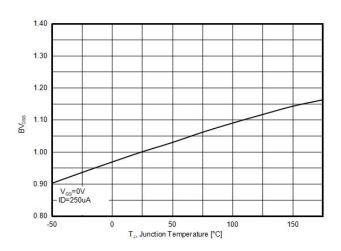




Figure 7. Maximum I<sub>D</sub> vs Junction Temperature

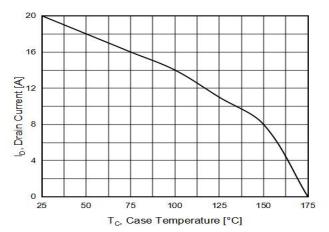


Figure8. Gate charge waveforms

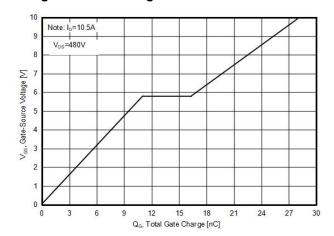


Figure 9. Static drain-source on resistance

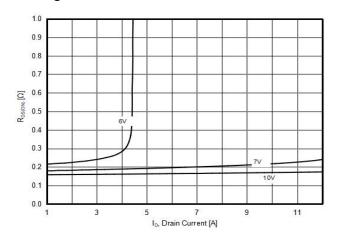
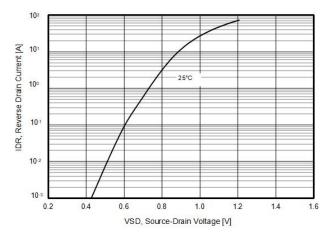


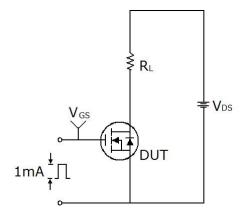
Figure 10. Source-Drain Diode Forward Voltage

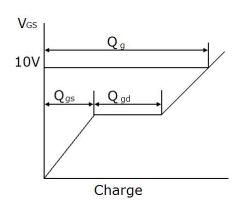




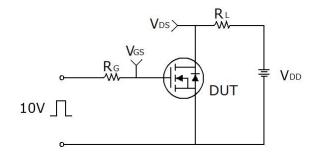
## **Test circuit**

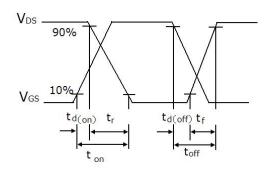
## 1) Gate charge test circuit & Waveform



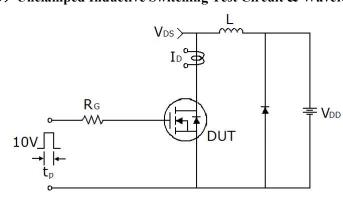


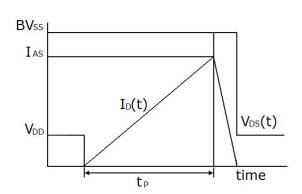
## 2) Switch Time Test Circuit:





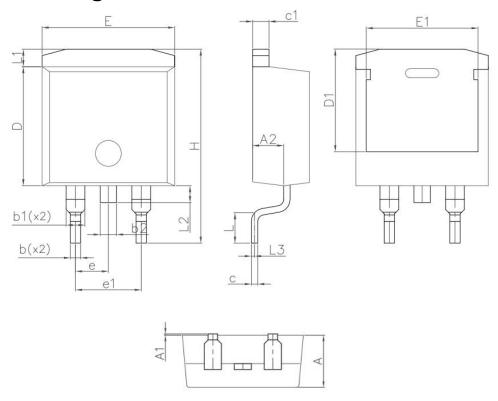
## 3) Unclamped Inductive Switching Test Circuit & Waveforms







# **TO-263-E Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.20	4.60	0.165	0.181	
A1	0.00	0.25	0.00	0.010	
A2	2.20	2.60	0.087	0.102	
b	0.70	0.90	0.028	0.035	
b1	1.20	1.75	0.047	0.069	
b2	1.17	1.37	0.046	0.054	
С	0.40	0.60	0.016	0.024	
c1	1.15	1.40	0.045	0.055	
D	9.10	9.30	0.358	0.366	
D1	7.63	8.23	0.300	0.324	
E	10.05	10.45	0.396	0.411	
E1	8.35	8.95	0.329	0.352	
е	2.54BSC		0.100BSC		
e1	5.08BSC		0.200	0.200BSC	
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	1.36	BREF	0.054REF		
L2	1.30	REF	0.051	REF	



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